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<i>PN</i>	AF	WO 02/17063 A2	04/04/02	WIPO			Yes      No
	AG						
OTHER REFERENCES (including Author, Title, Date, Pertinent Pages, Etc.)							
<i>\$2</i>	AH	'Atomic Layer Deposition of SiO <sub>2</sub> Using Catalyzed And Uncatalyzed Self-Limiting Surface Reactions'; J.W. Klaus et al; Surface Review					
		and Letters, Vol. 6, Nos. 3 & 4 (1999) pp. 435-448					
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		Thin Solid Films 397 (2001) pp. 78-82					
	AJ	'Reactive Deposition of Metal Thin Films within Porous Supports from Supercritical Fluids'; Neil E. Fernandes et al; Chem Mater. 2001;					
		13, pp. 2023-2031					
	AK	'Supercritical CO <sub>2</sub> Processing for Submicron Imagine of Fluoropolymers'; Narayan Sundararajan et al; Chem. Mater. 2000; 12;					
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	AL	'Supercritical carbon dioxide assisted aerosolization for thin film deposition, fine powder generation, and drug delivery'; C.Y. Xu et al.; P.T. Anastas; T.C. Williamson, Green Chemistry, S. pp. 313-335; Oxford University Press, Oxford 1998					
		'Supercritical Fluid Transport-Chemical Deposition of Films'; Brian N. Hansen et al; Chem Mater. 1992; 4; pp. 749-752					
<i>\$2</i>	AM						
EXAMINER		<i>John R. Da</i>		DATE CONSIDERED		<i>6/1/04</i>	
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